



Material Content Data Sheet



Sales Product Name		TLE5041PLUSC		Issued		31. July 2018		
MA#		MA001204578						
Package		PG-SSO-2-53		Weight*		167.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.257	0.75	0.75	7487	7487
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1718	
	non noble metal	titanium	7440-32-6	0.288	0.17		1718	
	non noble metal	nickel	7440-02-0	0.384	0.23		2290	
	non noble metal	tin	7440-31-5	0.577	0.34		3435	
	non noble metal	copper	7440-50-8	94.576	56.35	57.26	563398	572559
wire	noble metal	gold	7440-57-5	0.044	0.03	0.03	263	263
encapsulation	organic material	carbon black	1333-86-4	0.591	0.35		3520	
	plastics	epoxy resin	-	10.637	6.34		63365	
	inorganic material	silicondioxide	60676-86-0	47.866	28.51	35.20	285142	352027
leadfinish	non noble metal	tin	7440-31-5	6.247	3.72	3.72	37213	37213
plating	noble metal	silver	7440-22-4	1.029	0.61	0.61	6130	6130
glue	plastics	epoxy resin	-	0.104	0.06		619	
	noble metal	silver	7440-22-4	0.415	0.25	0.31	2474	3093
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		4	
	inorganic material	leadtitanate	12060-00-3	0.018	0.01		106	
	inorganic material	titandioxide	13463-67-7	0.085	0.05		507	
	inorganic material	bismuth trioxide	1304-76-3	0.147	0.09		875	
	noble metal	palladium	7440-05-3	0.273	0.16		1626	
	noble metal	silver	7440-22-4	0.858	0.51		5114	
	inorganic material	bariumtitanate	12047-27-7	2.182	1.30	2.12	12996	21228
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7 (c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

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